

Printed circuit board production and assembly services:

1. Professional engineers watching
2. The solder paste is made from reliable Sn96.5Ag3Cu0.5 silver-containing solder paste.
3. A variety of testing equipment: SPI solder paste thickness test, 100% AOI scanning full test, FQC full test, functional test.
4. BGA is X-ray tested throughout the production process and meets ISO requirements.

